

5-103817-2 ✓ ACTIVE

AMPMODU | AMPMODU Headers

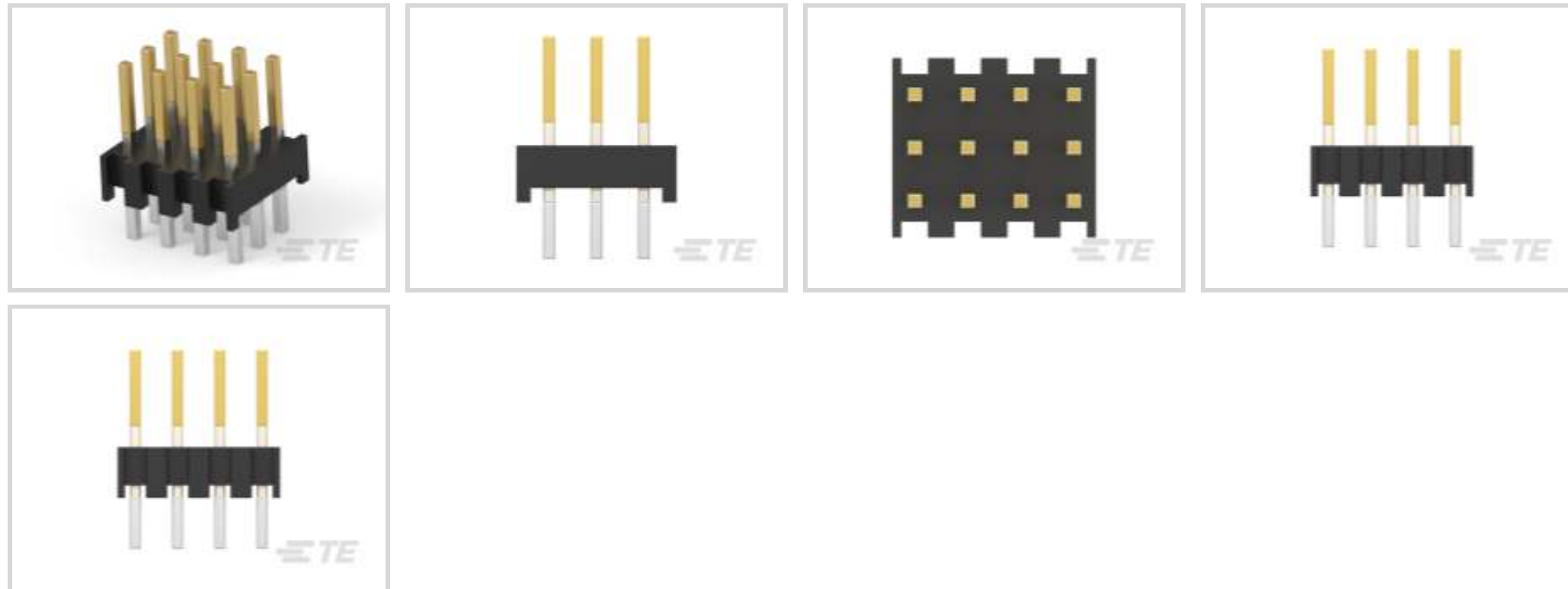
TE Internal #: 5-103817-2

PCB Mount Header, Vertical, Board-to-Board, 12 Position, 2.54 mm
[.1 in] Centerline, Unshrouded, Gold, Through Hole - Solder, Signal,
AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **12**

Number of Rows: **3**

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Unshrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	12
Number of Rows	3
Board-to-Board Configuration	Parallel

Electrical Characteristics

Insulation Resistance	5000 M Ω
Dielectric Withstanding Voltage (Max)	750 Vrms



Operating Voltage	30 VAC
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Body Features

Primary Product Color	Black
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Contact Features

Mating Square Post Dimension	.64 mm[.025 in]
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	10 – 20 μ m
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Contact Shape & Form	Square
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Contact Underplating Material	Nickel
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PCB Contact Termination Area Plating Material	Tin
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Contact Base Material	Phosphor Bronze
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Contact Mating Area Plating Material	Gold
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Contact Mating Area Plating Material Thickness	.76 μ m[30 μ m]
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Contact Type	Pin
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Contact Current Rating (Max)	3 A
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Termination Features

Square Termination Post & Tail Dimension	.64 mm[.025 in]
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Termination Post & Tail Length	3.05 mm[.12 in]
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Termination Method to Printed Circuit Board	Through Hole - Solder
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Mechanical Attachment

Mating Alignment	Without
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PCB Mount Retention	Without
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PCB Mount Alignment	Without
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Connector Mounting Type	Board Mount
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Housing Features

Centerline (Pitch)	2.54 mm[.1 in]
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Housing Material	Thermoplastic
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Dimensions

Row-to-Row Spacing	2.54 mm[.1 in]
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PCB Thickness (Recommended)	1.4 mm[.055 in]
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Usage Conditions

Housing Temperature Rating	Standard
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Operating Temperature Range	-55 – 125 °C[-67 – 257 °F]
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Operation/Application

Circuit Application	Signal
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Industry Standards

UL Rating	Recognized
Agency/Standard	CSA, UL
Approved Standards	CSA LR16455, UL E28476
UL Flammability Rating	UL 94V-0

Packaging Features

Packaging Quantity	100
Packaging Type	Carton

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.
Solder Process Capability	Wave solder capable to 240°C

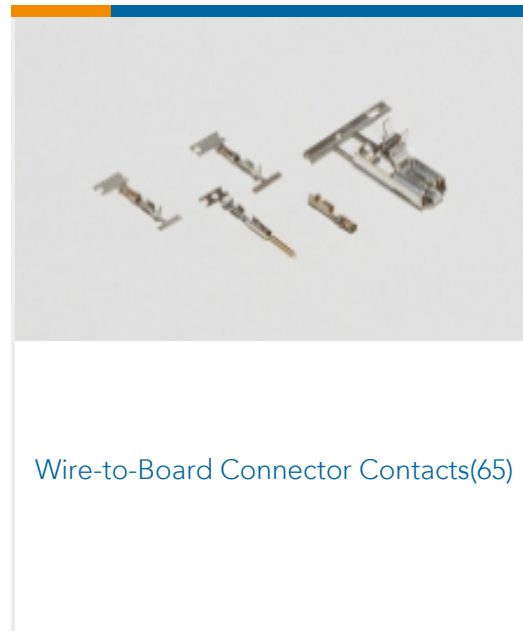
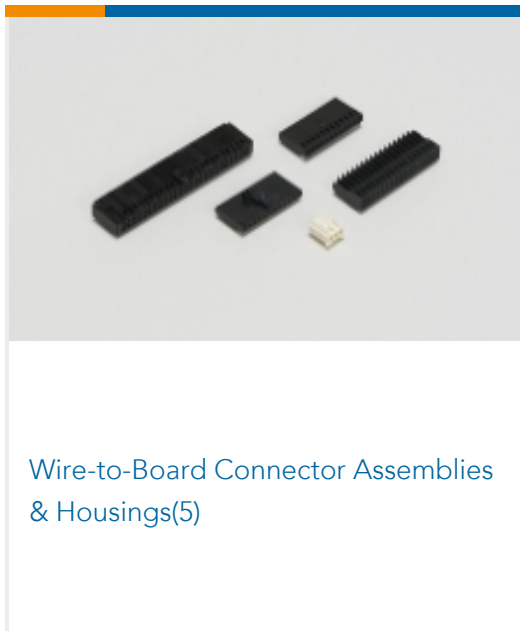
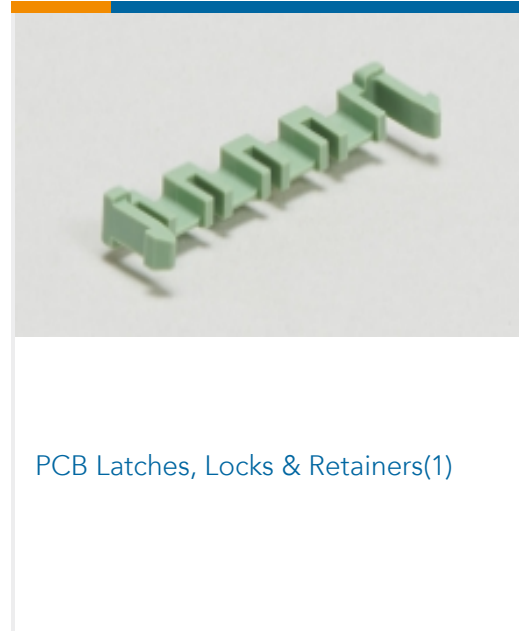
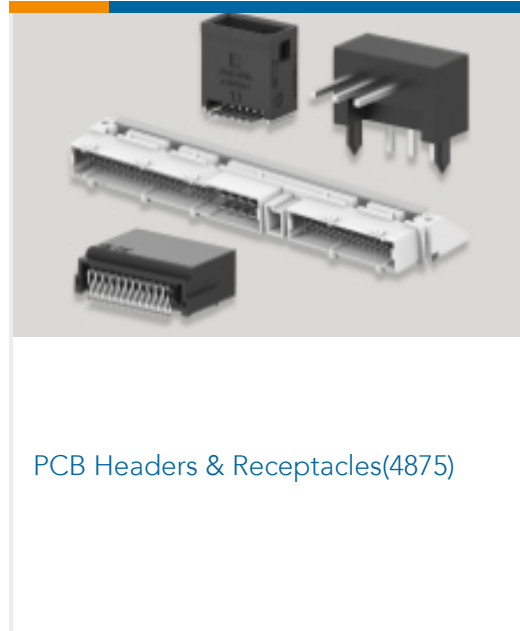
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

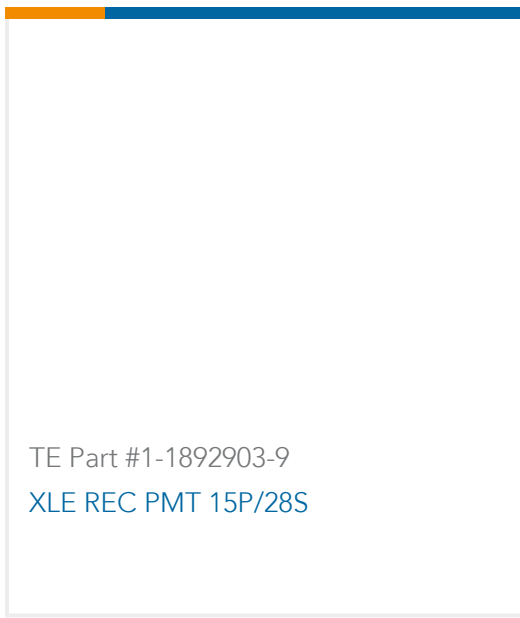


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Customers Also Bought





Documents

Product Drawings

[12 MODII HDR 3RST UNSHRD .100](#)

English

CAD Files

[3D PDF](#)

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[Customer View Model](#)

[ENG_CVM_5-103817-2_E1.3d_igs.zip](#)

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[ENG_CVM_5-103817-2_E1.3d_stp.zip](#)

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[Customer View Model](#)

[ENG_CVM_5-103817-2_E1.2d_dxf.zip](#)

English

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Datasheets & Catalog Pages

[AMPMODU_INTERCONNECTION_SYSTEM_SECTION5](#)

English

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